

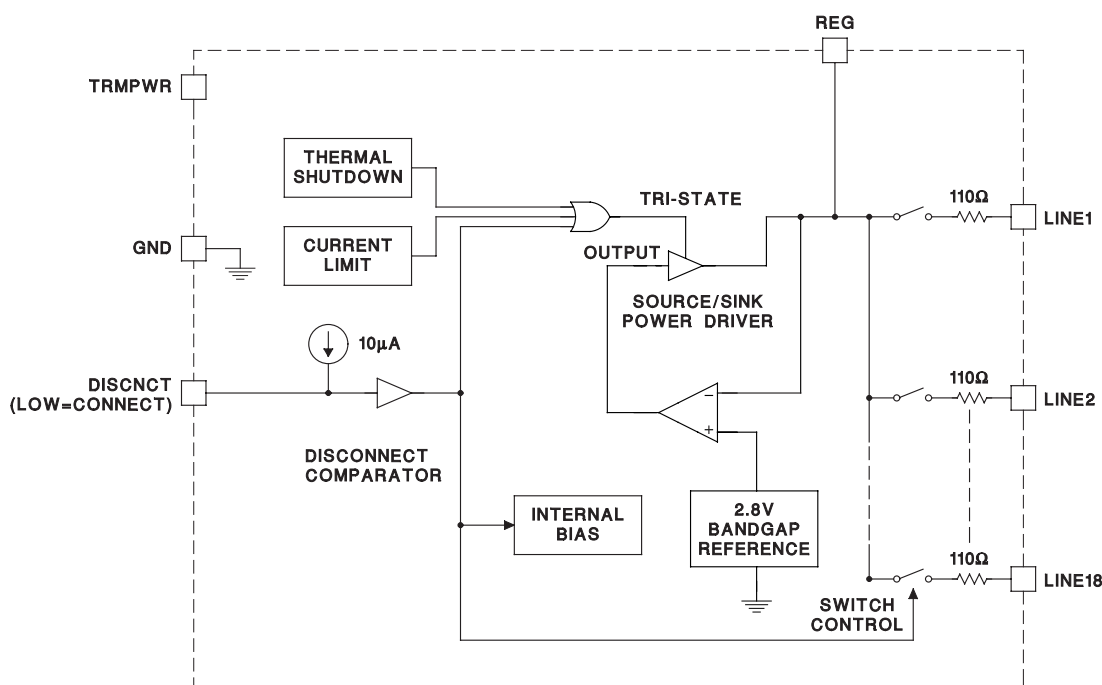
FEATURES

- Complies with SCSI, SCSI-2, SCSI-3, SPI and FAST-20 Standards
- 2pF Channel Capacitance During Disconnect
- 50 μ A Supply Current in Disconnect Mode
- 110 Ω Termination
- SCSI Hot Plugging Compliant, 10nA Typical
- +400mA Sinking Current for Active Negation
- -650mA Sourcing Current for Termination
- Trimmed Impedance to 5%
- Thermal Shutdown
- Current Limit

DESCRIPTION

This device is offered in low thermal resistance versions of the industry standard 28 pin wide body SOIC, TSSOP and PLCC.

BLOCK DIAGRAM



Patented Circuit Design

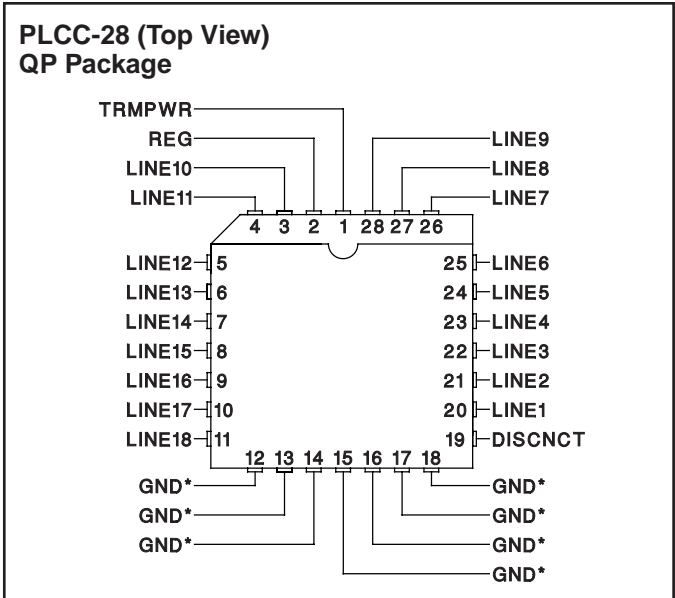
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ABSOLUTE MAXIMUM RATINGS

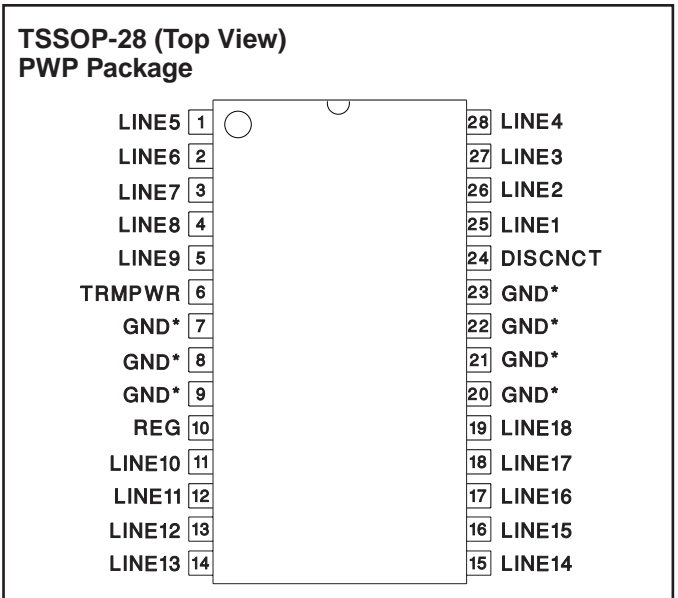
TEMPWR.	+7V
Signal Line Voltage	0V to +7V
Regulator Output Current	1A
Storage Temperature	–65°C to +150°C
Operating Junction Temperature	–55°C to +150°C
Lead Temperature (Soldering, 10 Seconds)	300°C

All currents are positive into, negative out of the specified terminal. Consult Packaging Section of Databook for thermal limitations and considerations of packages.

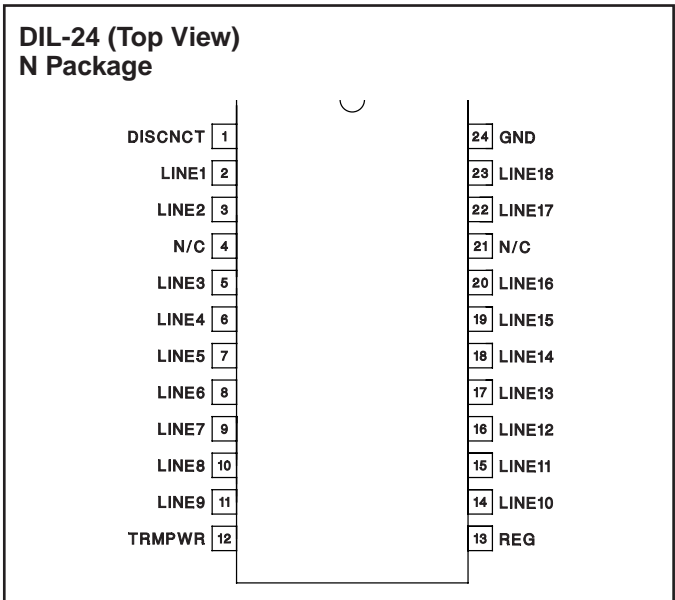
CONNECTION DIAGRAMS



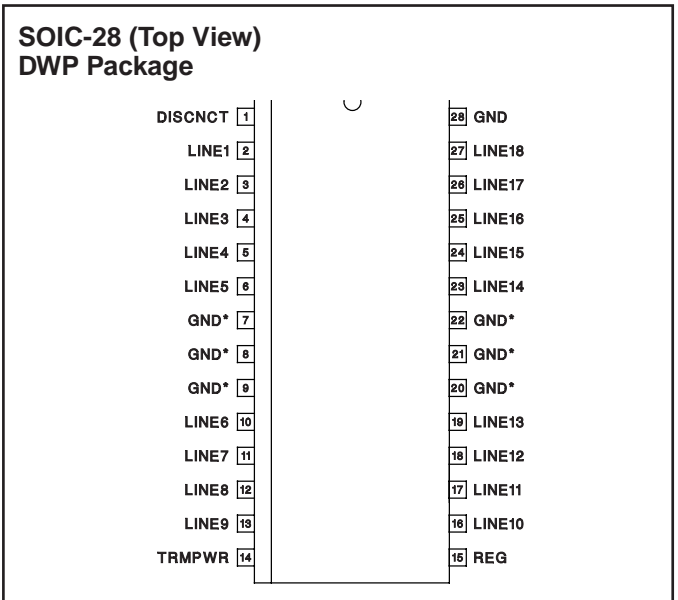
* DWP package pins 12–18 serve as both heatsink and signal ground.



* PWP package pin 23 serves as signal ground; pins 7, 8, 9, 20, 21, and 22 serve as heatsink ground.



Note: Drawings are not to scale.



* DWP package pin 28 serves as signal ground; pins 7, 8, 9, 20, 21, 22 serve as heatsink/ground.

ELECTRICAL CHARACTERISTICS: Unless otherwise stated these specifications apply for $T_A = 0^\circ\text{C}$ to 70°C , $\text{TRMPWR} = 4.75\text{V}$, $\text{DISCNCT} = 0\text{V}$, $T_A = T_J$.

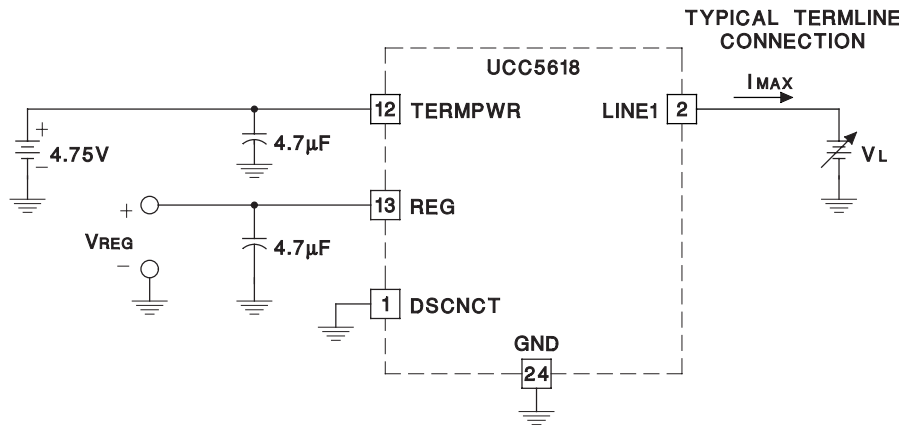
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Supply Current Section					
TERMPWR Supply Current	All Termination Lines = Open		1	2	mA
	All Termination Lines = 0.2V		420	440	mA
Power Down Mode	DISCNCT = TRMPWR		50	100	μA
Output Section (Termination Lines)					
Termination Impedance	See Figure 1	104.5	110	115.5	Ω
Output High Voltage	$V_{\text{TRMPWR}} = 4\text{V}$ (Note 1)	2.6	2.8	3	V
Max Output Current	$V_{\text{LINE}} = 0.2\text{V}$, $T_J = 25^\circ\text{C}$	-22.1	-23.3	-24	mA
	$V_{\text{LINE}} = 0.2\text{V}$	-20.7	-23.3	-24	mA
	$V_{\text{LINE}} = 0.2\text{V}$, $\text{TERMPWR} = 4\text{V}$, $T_J = 25^\circ\text{C}$ (Note 1)	-21	-23.3	-24	mA
	$V_{\text{LINE}} = 0.2\text{V}$, $\text{TRMPWR} = 4\text{V}$ (Note 1)	-20	-23	-24	mA
	$V_{\text{LINE}} = 0.5\text{V}$			-22.4	mA
Output Leakage	DISCNCT = 2.4V, TRMPWR = 0V to 5.25V, REG = 0.2V, $V_{\text{LINE}} = 5.25\text{V}$		10	400	nA
Output Capacitance	DISCNCT = 2.4V (Note 2)		2	3.5	pF
Regulator Section					
Regulator Output Voltage		2.6	2.8	3	V
Drop Out Voltage	All Termination Lines = 0.2V		0.4	0.8	V
Short Circuit Current	$V_{\text{REG}} = 0\text{V}$	-475	-650	-950	mA
Sinking Current Capability	$V_{\text{REG}} = 3.5\text{V}$	200	400	800	mA
Thermal Shutdown			170		$^\circ\text{C}$
Thermal Shutdown Hysteresis			10		$^\circ\text{C}$
Disconnect Section					
Disconnect Threshold		0.8	1.5	2	V
Input Current	DISCNCT = 0V		-10	-30	μA

Note 1: Measuring each termination line while other 17 are low (0.2V).

Note 2: Guaranteed by design. Not 100% tested in production.

Procedure:

- 1) Measure V_{REG} N.L.
- 2) Set $V_L = 0.2\text{V}$
- 3) Measure I_{MAX} at 0.2V
- 4) Impedance = $\frac{V_{\text{REG N.L.}} - 0.2\text{V}}{I_{\text{MAX}}}$



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Figure 1. Termline Impedance Measurement Circuit

PIN DESCRIPTIONS

DISCNCT: Taking this pin high or leaving it open causes the 18 channels to become high impedance and the chip to go into low-power mode; a low state allows the channels to provide normal termination.

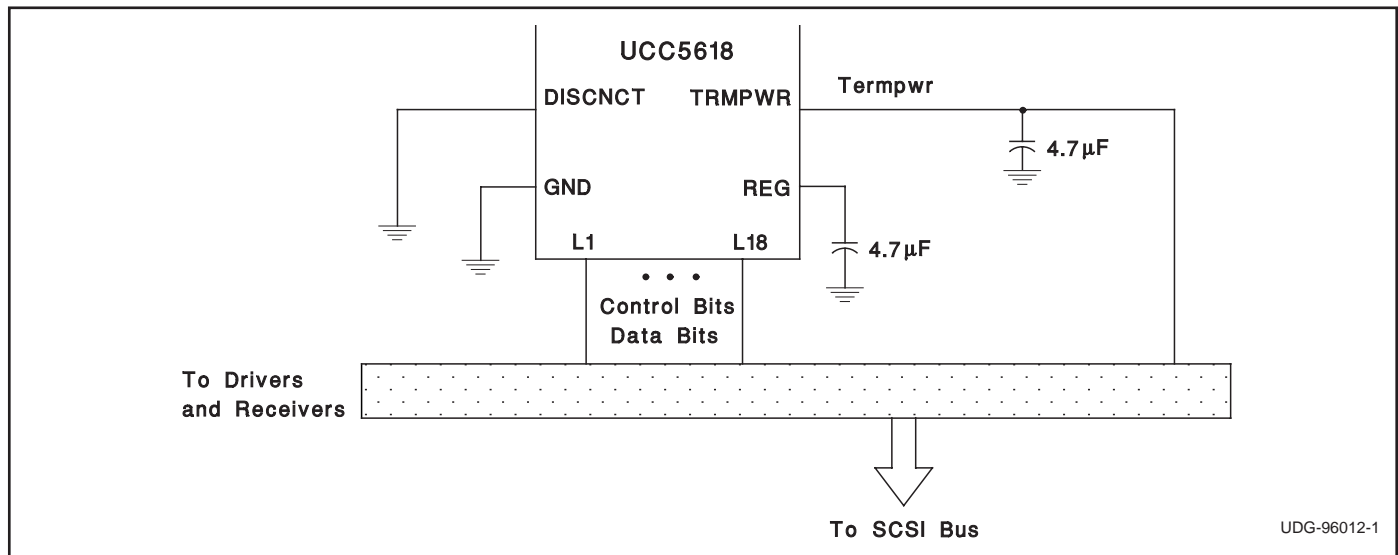
GND: Ground reference for the IC.

LINE1–LINE18: 110Ω termination channels.

REG: Output of the internal 2.8V regulator.

TRMPWR: Power for the IC.

APPLICATION INFORMATION



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